



HE9014

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HE9014 is designed for use in pre-amplifier of low level and low noise.

Features

- High Total Power Dissipation (PD: 450mW)
- Complementary to HE9015
- High hFE and Good Linearity

Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 450 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage 50 V
 VCEO Collector to Emitter Voltage 45 V
 VEBO Emitter to Base Voltage 5 V
 IC Collector Current 100 mA

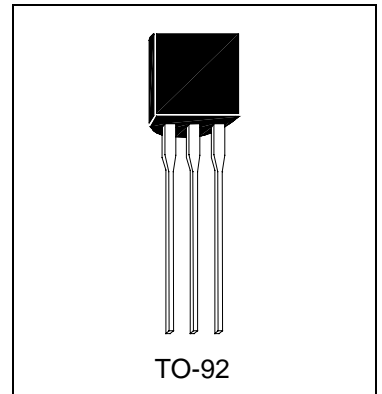
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	50	-	-	V	IC=100uA, IE=0
BVCEO	45	-	-	V	IC=1mA, IB=0
BVEBO	5	-	-	V	IE=100uA, IC=0
ICBO	-	-	50	nA	VCB=50V, IE=0
IEBO	-	-	50	nA	VEB=5V, IC=0
*VCE(sat)	-	0.14	0.3	V	IC=100mA, IB=5mA
*VBE(sat)	-	0.84	1	V	IC=100mA, IB=5mA
VBE(on)	0.58	0.63	0.7	V	VCE=5V, IC=2mA
*hFE	100	280	1000		VCE=5V, IC=1mA
Cob	-	2.20	3.5	pF	VCB=10V, f=1MHz, IE=0
fT	150	270	-	MHz	VCE=5V, IC=10mA

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

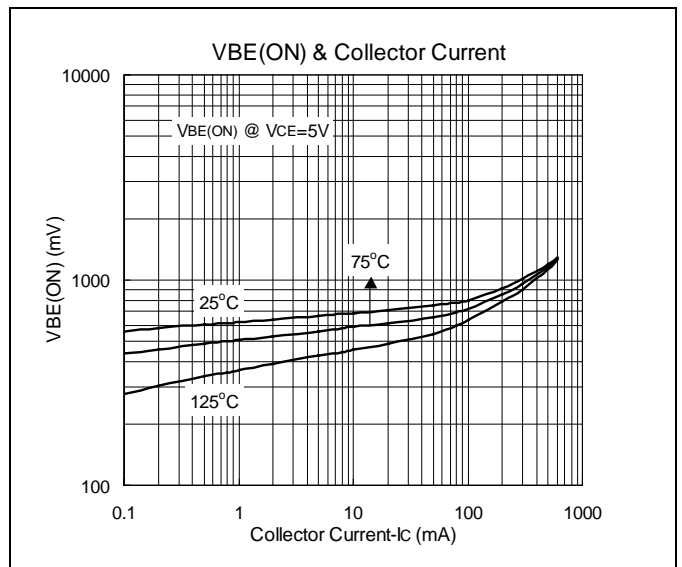
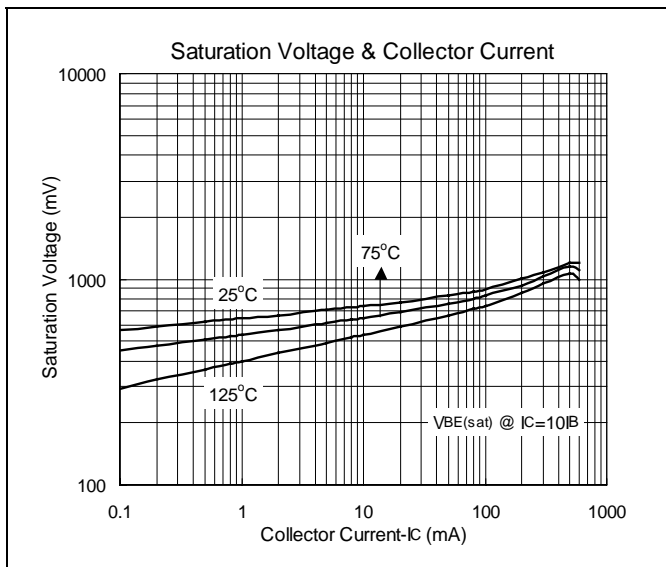
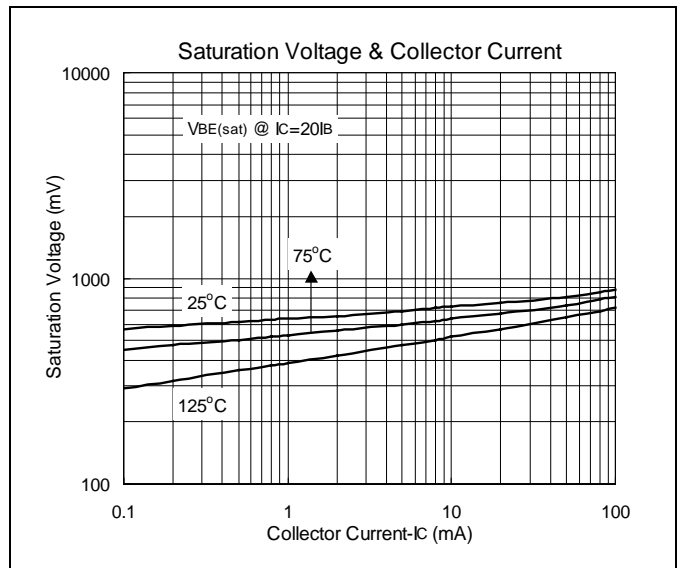
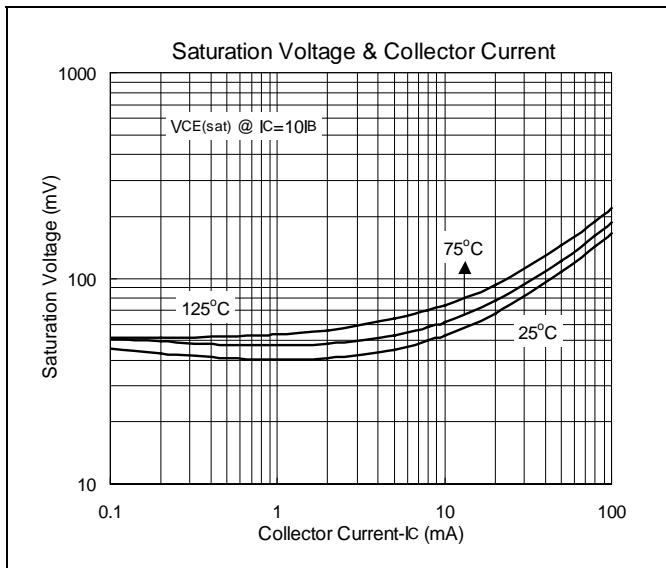
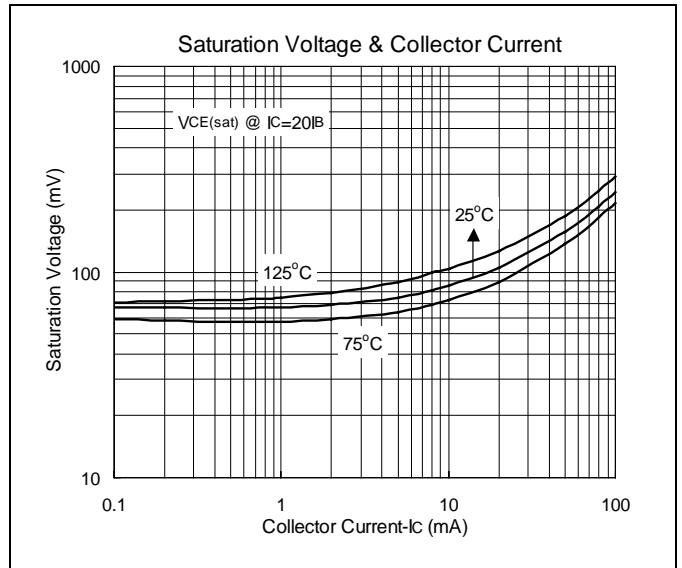
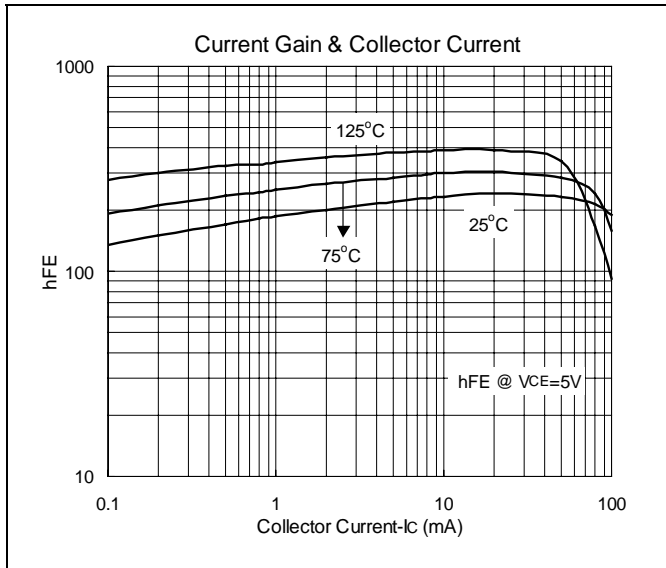
Classification on hFE

Rank	B	C	D
Range	100-300	200-600	400-1000



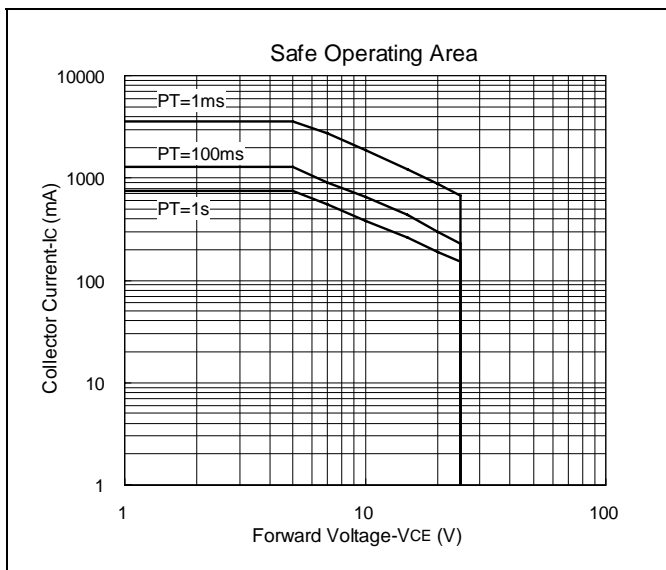
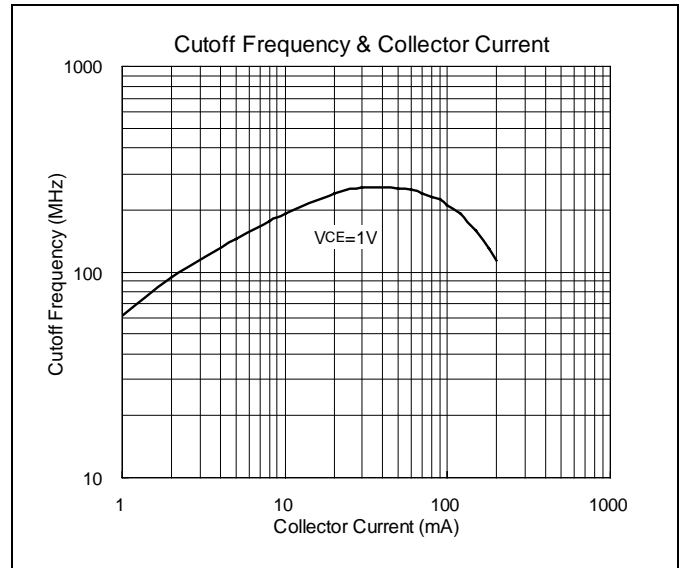
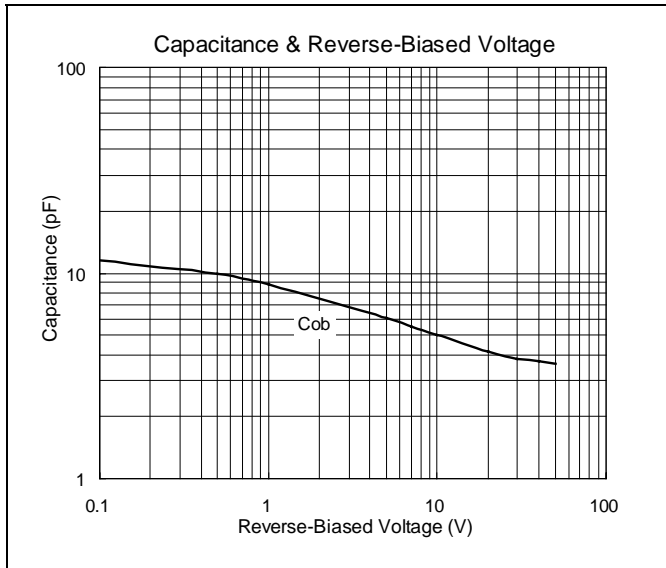


Characteristics Curve



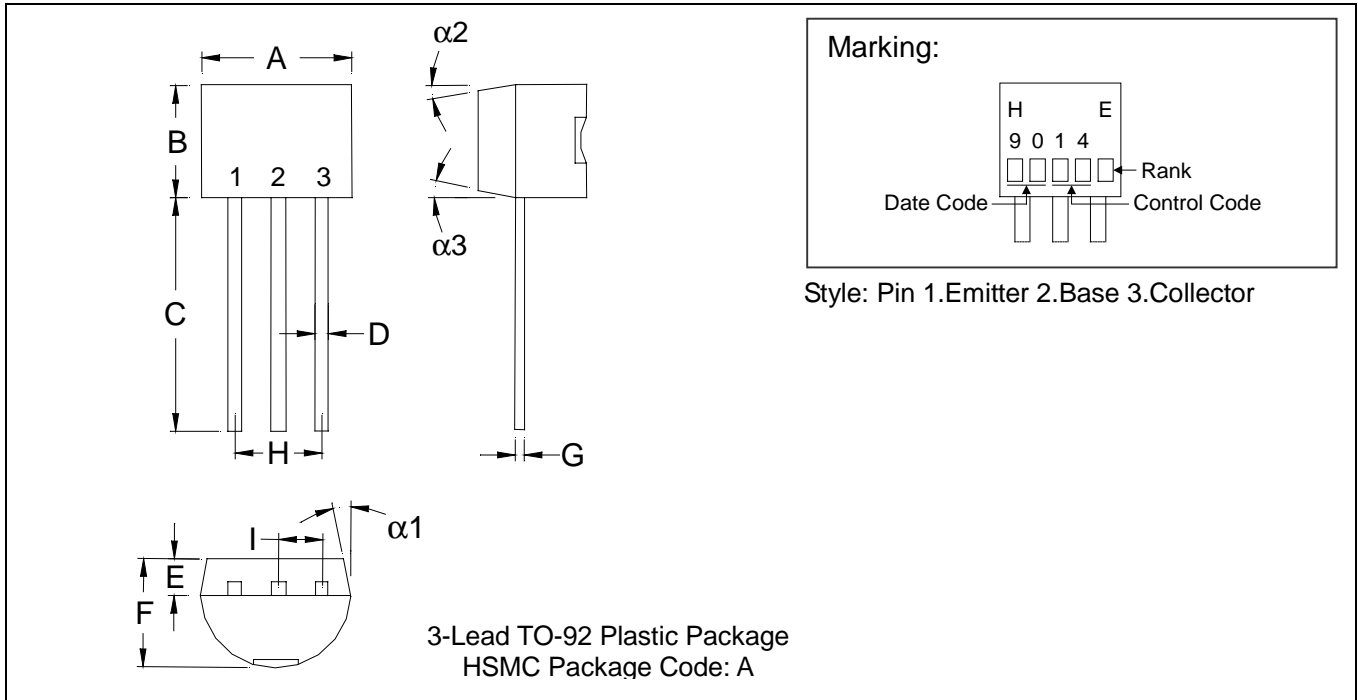


Characteristics Curve





TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931